

Description

The IPD042P03L3 G uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

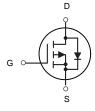


TO-252-2L

General Features

 $V_{DS} = -30V$ $I_{D} = -120A$

 $R_{DS(ON)}$ <4.5m Ω @ V_{GS} =-10V



P-Channel MOSFET

Application

Lithium battery protection

Wireless impact

Mobile phone fast charging

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
IPD042P03L3 G	TO-252-2L	HXY MOSFET	2500

Absolute Maximum Ratings (TC=25℃unless otherwise noted)

Symbol	Parameter	Max.	Units	
VDSS	Drain-Source Voltage	-30	V	
VGSS	Gate-Source Voltage	±20	V	
ID	Continuous Drain Current T _C = 25°C	-120	А	
ID	Continuous Drain Current T _C = 100°C	-80	А	
IDM	Pulsed Drain Current note1	-470	А	
EAS	Single Pulsed Avalanche Energy note2	580	mJ	
PD	Power Dissipation T _C = 25°C	100	W	
RθJC	Thermal Resistance, Junction to Case	1.4	°C/W	
TJ, TSTG	Operating and Storage Temperature Range	-55 to +175	°C	



Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =-250μA	-30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-30V, V _{GS} =0V			-1	μΑ
Igss	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-1 -1.7		-2.5	V
G FS	Forward Transconductance	V _{DS} =-5V, I _D =-20A		65		S
Rds(on)	Drain-Source On-State Resistance	V _{GS} =-10V, I _D =-20A		3.7	4.5	mΩ
		V _{GS} =-4.5V, I _D =-20A		6	8.2	mΩ
Ciss	Input Capacitance			7000		pF
Coss	Output Capacitance	V _{DS} =-15V, V _{GS} =0V, f=1.0MHz		820		pF
Crss	Reverse Transfer Capacitance			540		pF
Rg	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1.0MHz		2.2		Ω
t _{d(on)}	Turn-on Delay Time			14		nS
tr	Turn-on Rise Time	V _{GS} =-10V, V _{DS} =-15V,		13		nS
t _{d(off)}	Turn-Off Delay Time	$R_L=0.75\Omega$, $R_{GEN}=3\Omega$		65		nS
t _f	Turn-Off Fall Time			37		nS
Qg	Total Gate Charge			130		nC
Q _{gs}	Gate-Source Charge	V _{GS} =-10V, V _{DS} =-15V, I _D =-20A		12		nC
Q_{gd}	Gate-Drain Charge			31		nC
I _{SD}	Source-Drain Current (Body Diode)				-108	Α
V _{SD}	Forward on Voltage (Note 3)	V _{GS} =0V, I _S =-20A			-1.2	V
t _{rr}	Reverse Recovery Time	I _F =-20A, di/dt=100A/μs		30		ns
Qrr	Reverse Recovery Charge	I _F =-20A, di/dt=100A/μs		40		nC

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

Notes $2.E_{AS}$ condition: T_J = $25^{\circ}C$, V_{DD} =15V, V_{G} =-10V, Rg= 25Ω , L=0.5mH. Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.



Typical Electrical And Thermal Characteristics (Curves)

Figure 1. Output Characteristics

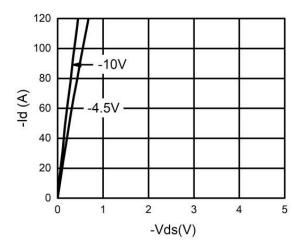


Figure 3. Power Dissipation

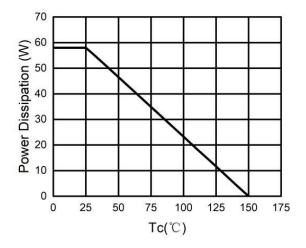


Figure 5. BV_{DSS} vs Junction Temperature

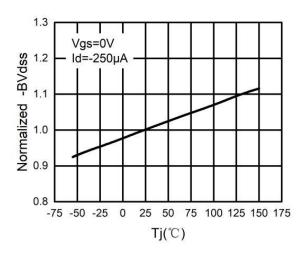


Figure 2. Transfer Characteristics

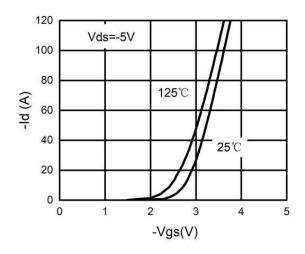


Figure 4. Drain Current

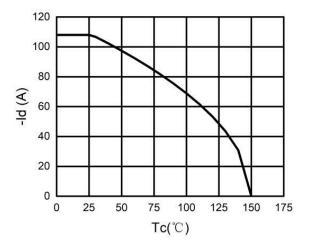


Figure 6. R_{DS(ON)} vs Junction Temperature

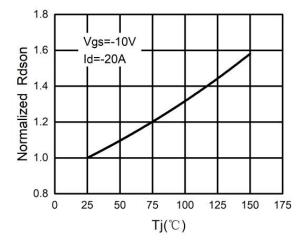




Figure 7. Gate Charge Waveforms

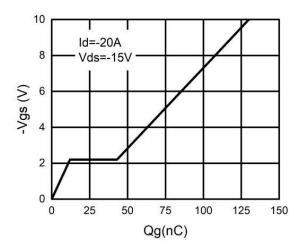


Figure 8. Capacitance

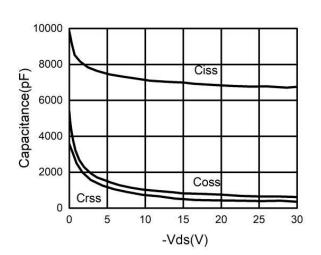


Figure 9. Body-Diode Characteristics

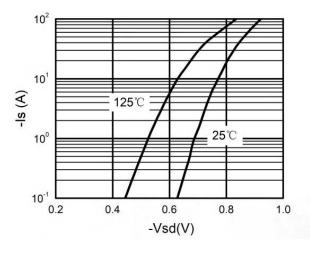
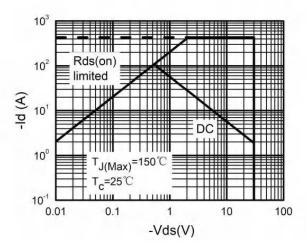
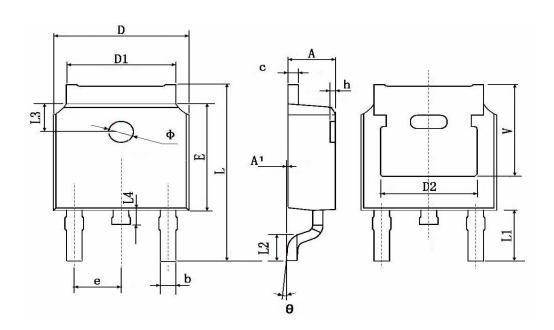


Figure 10. Maximum Safe Operating Area



TO-252-2L Package Information



Dimensions In Millimeters		Dimensions In Inches			
Min.	Max.	Min.	Max.		
2.200	2.400	0.087	0.094		
0.000	0.127	0.000	0.005		
0.660	0.860	0.026	0.034		
0.460	0.580	0.018	0.023		
6.500	6.700	0.256	0.264		
5.100	5.460	0.201	0.215		
4.830 TYP.		0.190 TYP.			
6.000	6.200	0.236	0.244		
2.186	2.386	0.086	0.094		
9.800	10.400	0.386	0.409		
2.900 TYP.		0.114 TYP.			
1.400	1.700	0.055	0.067		
	1.600 TYP.		0.063 TYP.		
0.600	1.000	0.024	0.039		
1.100	1.300	0.043	0.051		
0°	8°	0°	8°		
0.000	0.300	0.000	0.012		
5.350	5.350 TYP. 0.211 TYP.		TYP.		
	Min. 2.200 0.000 0.660 0.460 6.500 5.100 4.830 6.000 2.186 9.800 2.900 1.400 1.600 0.600 1.100 0° 0.000	Min. Max. 2.200 2.400 0.000 0.127 0.660 0.860 0.460 0.580 6.500 6.700 5.100 5.460 4.830 TYP. 6.200 2.186 2.386 9.800 10.400 2.900 TYP. 1.700 1.600 TYP. 0.600 1.100 1.300 0° 8° 0.000 0.300	Min. Max. Min. 2.200 2.400 0.087 0.000 0.127 0.000 0.660 0.860 0.026 0.460 0.580 0.018 6.500 6.700 0.256 5.100 5.460 0.201 4.830 TYP. 0.190 6.000 6.200 0.236 2.186 2.386 0.086 9.800 10.400 0.386 2.900 TYP. 0.114 1.400 1.700 0.055 1.600 TYP. 0.063 0.600 1.000 0.024 1.100 1.300 0.043 0° 8° 0° 0.000 0.300 0.000		



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